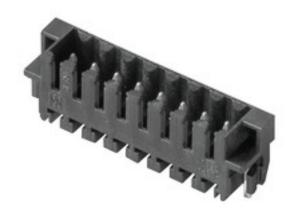


Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image

















Similar to illustration

High-temperature-resistant male header, 3.50 mm pitch.

- Plugging direction parallel (90°), straight 180° or angled (135°) to PCB
- Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)
- Optimised for the SMT process
- Pin length 3.2 mm universal for all soldering methods
- Pin length 1.5 mm optimised for reflow soldering methods
- Packed either in a box (BX) or tape-on-reel (RL)
- Male header can be coded

General ordering data

PCB plug-in connector, male header, Clip-on flange, THT/THR solder connection, 3.50 mm, Number of poles: 12, 180°, Solder pin length (I): 1.5 mm, tinned, black, Tape
flange, THT/THR solder connection, 3.50 mm, Number of poles: 12, 180°, Solder pin length (I): 1.5 mm, tinned, black, Tape
Number of poles: 12, 180°, Solder pin length (I): 1.5 mm, tinned, black, Tape
1.5 mm, tinned, black, Tape
<u>2591920000</u>
SL-SMT 3.50/12/180RF 1.5SN BK RL CO
4050118600049
230 pc(s).
IEC: 320 V / 15 A
UL: 300 V / 10 A
Tape



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Technical data

Dimensions and weights

Depth	7.4 mm	Depth (inches)	0.291 inch
Height	12.6 mm	Height (inches)	0.496 inch
Height of lowest version	11.1 mm	Width	48.86 mm
Width (inches)	1.924 inch	Net weight	3.928 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connec-	Pitch in mm (P)	
	tion		3.5 mm
Pitch in inches (P)	0.138 "	Outgoing elbow	180°
Number of poles	12	Number of solder pins per pole	1
Solder pin length (I)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm
Solder eyelet hole diameter (D)	1.4 mm	Solder eyelet hole diameter tolerance (I	D)+ 0,1 mm
Outside diameter of solder pad	2.3 mm	Template aperture diameter	2.1 mm
L1 in mm	38.5 mm	L1 in inches	1.516 "
Number of rows	1	Pin series quantity	1
Touch-safe protection acc. to DIN VDE 57 106	finger-safe plugged/ back- of-hand-safe unplugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 un- plugged
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging cycles	25	Plugging force/pole, max.	6 N
Pulling force/pole, max.	6 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	Cu-alloy	Contact surface	tinned
Layer structure of solder connection	23 µm Ni	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	12 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage		Rated impulse voltage for surge voltage	
class/ pollution degree II/2	2.5 kV	class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage			
class/ contamination degree III/3	2.5 kV		

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A

Creation date June 12, 2025 11:19:04 AM CEST



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Technical data

Rated data acc. to UL 1059

Rated voltage (Use group B / UL 1059) 300 V	Rated voltage (Use group D / UL 1059) 300 V
Rated current (Use group B / UL 1059) 10 A	Rated current (Use group D / UL 1059) 10 A

Packing

ESD Level packaging	static dissipative	Packaging	Tape
VPE length	332 mm	VPE width	332 mm
VPE height	95 mm	Tape depth (T2)	16.5 mm
Tape width (W)	88 mm	Tape pocket depth (K0)	16 mm
Tape pocket height (A0)	7.8 mm	Tape pocket width (B0)	71.8 mm
Tape pocket separation (P1)	16 mm	Tape hole separation (E)	1.75 mm
Tape pocket separation (F)	42.2 mm	Tape reel diameter Ø (A)	330 mm
Surface resistance	$Rs = 10^9 - 10^{12} \Omega$	Width Pick & Place Pad (W _{PPP})	6.8 mm
Length Pick & Place Pad (L _{PPP})	_	Diameter of the withdrawal surface (ø	
	12.65 mm	D _{max})	5 mm
Protrusion 1 Pick & Place Pad (L _{O1 (PPP)})	2.7 mm	Protrusion 2 Pick & Place Pad (P _{O2 (PPP)})	2.5 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
ECLASS 13.0	27-46-02-01	ECLASS 14.0	27-46-02-01
ECLASS 15.0	27-46-02-01		

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized stan- dards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	Gold-plated contact surfaces on request
	Rated current related to rated cross-section & min. No. of poles.

- Diameter of solder eyelet D = 1.4+0.1mm
- Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles
- P on drawing = pitch
- · Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load
- Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months



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Technical data

Downloads

Product Change Notification	Changeover to ESD bags for "Tape on Reel" products
	Umstellung auf ESD-Beutel bei "Tape on Reel" Produkten
Catalogues	Catalogues in PDF-format
White paper surface mount technology	Download Whitepaper



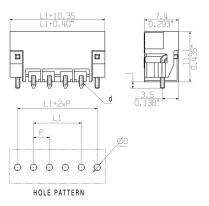
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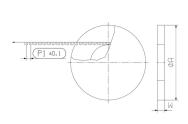
Drawings

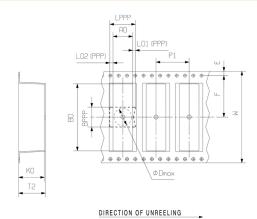
Dimensional drawing



Dimensional drawing

Dimensional drawing



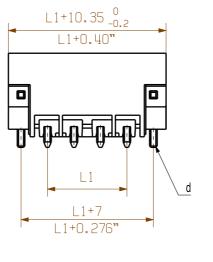


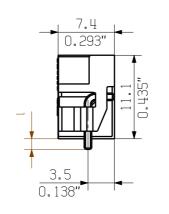
Example of use

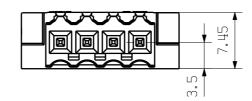
Example of use



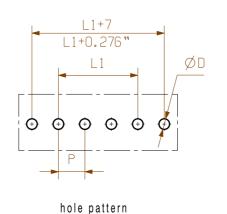


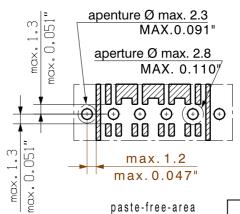












pin length I	tolerance
1,5	0,0
1,5	-0,3
2,6	0,0
	-0,3
3,2	0,0
	-0,3
4,5	0,0
4,5	-0.3

24	80,	50	3,169						
23	77,	00	3,031	+/- 0.2					
22	73,	50	2,894						
21	70,	00	2,756						
20	66,	50	2,618						
19	63,	00	2,480						
18	59,	50	2,343						
17	56,	00	2,205						
16	52,	50	2,067						
15	49,	00	1,929						
14	45,	50	1,791						
13	42,	00	1,654						
12	38,50 35,00		1,516	+/- 0.15					
11			35,00 1,378		17- 0.13				
10	31,	50	1,240						
9	28,	00	1,102						
8	24,50 21,00		0,965						
7			0,827						
6	17,50		0,689	+/- 0.1					
5	14,00		14,00		14,00 0,551		+/- U. I		
4	10,50		10,50 0,413		0,413				
4		7,00 0,276							
3	7,0	10	0,270]					
-	7,0 3,5		0,138						
3		0	,	tolerance					

shown: SL-SMT 3.50/04/180RF

For the mounting of PCBs, it should be noted that the rated data given in the catalogue relates only to the connection elements. The neccessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller connectors are tested to the DIN VDE 0627 standard, and are valid for its field of application. Provided that the connectors are used to the intended purpose, all requirements with respect to the occuring of electrical, mechanical, thermic and corrosive stress will be satisfied.

GENERAL TOLERANCE:								
DIN ISO 2768-mK	99546/5 08.12.17 HELIS_MA		0 0	Weidmü		ller	F	
COMPLIANT	Modification							
		Date		Name	SL-SM			
	Drawn	28.11.20	007	HELIS_MA			T 3 5	
	Responsible			AMANN_A		O IVI	STIFTL	
Scale: 2:1	Checked	05.01.20	018	HERTEL_S			MALE H	
Supersedes:	Approved			LANG T	Product file:	SL-SMT	3.50	

SL-SMT 3.50/../180... MALE HEADER Product file: SL-SMT 3.50

Sheet 05 of 05 sheets

Drawing no.

Issue no

7312



Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.



Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- · Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.